

CLAIM AMENDMENTS

1. (Currently Amended) A method of manufacturing a device package in which a device is electrically connected to external wiring through a metal wire, ~~said the~~ method comprising:

forming a small-diameter ball ~~by~~ using a small-diameter metal wire, bonding said small-diameter ball to ~~said the~~ device, and then separating said small-diameter metal wire from said small-diameter ball;

forming a large-diameter ball ~~by~~ using a large-diameter metal wire, and bonding said large-diameter ball to ~~said the~~ external wiring, said small-diameter ball and metal wire having respective diameters smaller than respective diameters of said large-diameter ball and metal wire; and

bonding said large-diameter metal wire ~~connecting with~~ connected to said large-diameter ball to said small-diameter ball by stitch bonding, and then separating said large-diameter metal wire from said small-diameter ball.

2. (Original) The method according to claim 1, wherein the diameter of said large-diameter metal wire is approximately equal to the diameter of said small-diameter ball.

3. (Currently Amended) The method according to claim 2, wherein said large-diameter metal wire is bonded to said small-diameter ball ~~such so that the height of the~~ a top portion of said large-diameter metal wire is approximately equal to the height co-planar with a top portion of said small-diameter ball.

4. (Currently Amended) A device package ~~in which a~~ comprising:
~~a device is~~ electrically connected to external wiring through a metal wire, ~~said device package comprising:~~
a small-diameter ball ~~which is~~ bonded to said device; and
a large-diameter ball ~~which is~~, having a larger diameter than said small-diameter ball, bonded to ~~said the~~ external wiring, wherein said small-diameter ball is connected to said large-diameter ball through said metal wire ~~while the height of and~~ and said small-diameter ball is approximately equal to the height of co-planar with said metal wire.